

**CERTIFICATE OF MAILING BY "EXPRESS MAIL" (37 CFR 1.10)**Applicant(s): **Sudhakar BOBBA et al.**

Docket No.

**03226/147001; P6841**

Serial No.

**09/997,438**

Filing Date

**November 29, 2001**

Examiner

**L. Cruz**

Group Art Unit

**2827**Invention: **150 DEGREE BUMP PLACEMENT LAYOUT FOR AN INTEGRATED CIRCUIT POWER GRID**I hereby certify that this **Reply Under 37 CFR 1.116 with Substitute Specification**

(Identify type of correspondence)

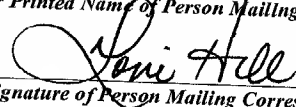
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**AMENDMENT TRANSMITTAL LETTER (Large Entity)**

Applicant(s): **Sudhakar BOBBA et al.**

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**L. Cruz**

Group Art Unit  
**2827**



Inventor: **150 DEGREE BUMP PLACEMENT LAYOUT FOR AN INTEGRATED CIRCUIT POWER GRID**

**TO THE ASSISTANT COMMISSIONER FOR PATENTS:**

Transmitted herewith is an amendment in the above-identified application.  
The fee has been calculated and is transmitted as shown below.

**CLAIMS AS AMENDED**

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	22 -	22 =	0 x	\$18.00	\$0.00
INDEP. CLAIMS	4 -	4 =	0 x	\$84.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00

- ☒ No additional fee is required for amendment.
- ☐ Please charge Deposit Account No. \_\_\_\_\_ in the amount of \_\_\_\_\_  
A duplicate copy of this sheet is enclosed.
- ☐ A check in the amount of \_\_\_\_\_ to cover the filing fee is enclosed.
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  - ☒ Any additional filing fees required under 37 C.F.R. 1.16.
  - ☒ Any patent application processing fees under 37 CFR 1.17.

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Dated: **3/7/03**

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U.S. PATENT APPLICATION NO. 09/997,438  
ATTORNEY DOCKET NO.: 03226.147001/P6841

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Sudhakar BOBBA et al.  
Serial No.: 09/997,438  
Filed : November 29, 2001  
Title : 150 DEGREE BUMP PLACEMENT LAYOUT FOR AN INTEGRATED CIRCUIT POWER GRID

Art Unit : 2827  
Examiner : Lourdes CRUZ

Assistant Commissioner for Patents  
Washington, DC 20231

**REPLY UNDER 37 CFR § 1.116**

Dear Sir:

In response to the final Office Action dated January 24, 2003, please amend the application as follows and consider the included remarks.

**IN THE CLAIMS:**

Please amend claims 1, 6, 11, and 17 as follows [a marked-up copy of the amended claims is provided in Appendix A]:

- 1 (Twice Amended) An integrated circuit having a top metal layer, the top metal layer having a first metal bar and a second metal bar, the integrated circuit comprising:
  - a first bump disposed on the first metal bar;
  - a second bump disposed on the first metal bar, wherein the second bump is adjacent to the first bump; and
  - a reference bump disposed on the second metal bar,wherein the first bump and the second bump are positioned such that an angle between a line from the reference bump to the first bump and a line from the reference bump to the second bump has a value substantially equal to 150 degrees.
- 6 (Twice Amended) An integrated circuit having a top metal layer, the top metal layer having a first metal bar and a second metal bar, the integrated circuit comprising:
  - a first bump disposed on the first metal bar;

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